

**HANDBOOK** OF INTEGRATED  
CIRCUITS

# HANDBOOK

# **OF INTEGRATED CIRCUITS**



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# Contents

## 1 Fundamentals of Solid-State Integrated Circuits, 3

*Definition, 3. Microelectronics, 3. Structure and design fundamentals, 7. Supporting technologies, 8. Technological backgrounds, 10. Design-Engineering-Circuitry, 12. Packaging, 14. LSI, 14.*

## 2 Surface Physics and Atomic Structure in Semiconductors, 17

*Introduction, 17. Crystal-surface physics, 19. The surface physics of semiconductor junctions, 26. Rectification—how a junction works, 30. Special diode action, 34.*

## 3 Semiconductors Materials and Junction Formation, 37

*Introduction, 37. Reduction, refining, and crystal growing, 37. Junction formation, 39. Point contact or bonded surface diodes, 40. Grown junction diodes and transistors, 41. Fused or alloy junction transistors, 43. Diffusion and epitaxial junction formation, 43. MOS thin-film silicon junctions, 45. Electrochemically formed junctions, 46. Junctions in IC formation, 46. Molecular processes in IC's, 48. Practical consideration summary, 50.*

## 4 IC Structure and Component Formation, 53

*Wafers and dice, 53. Design requirements, 56. Formation of the components, 57. Transistor fabrication, 57. Component fabrication, 62.*

## 5 Transistor and Diode Engineering in Integrated Circuits, 69

*Introduction, 69. Transistors in IC's, 69. Alpha deviation, 70. Physics of interacting junctions, 72. Power gain, 75. Transistor terminology, 77. Transistor ratings and characteristic data, 77. Transistor characteristics, 78. Diodes in an integrated circuit, 80. General-purpose diodes, 83. Switching diodes, 84.*

## 6 Basic IC Construction, 87

*Introduction-organization, 87. The basic IC structure and processes, 89. Fundamental molecular processes, 92. Molecular processes in IC fabrication, 93. Processing and equipment, 96. Summary, 100.*

## **7 Photo thography, Masking, and Photoreduction, 103**

*Introduction, 103. Photolithography, 103. Photoreduction-mask formation, 107. The masking sequence, 112. IC pattern dimensions, 115. Details of component mask making, 116. Summary, 121.*

## **8 Thin-Film, Hybrid, and Printed-Circuit Technology, 123**

*Introduction, 123. Thin-film components, 123. Thin-film capacitors, 131. Fabrication Processing, 131. Hybrid assemblies, 135. Printed circuits, 136. Etched printed circuits, 137. Plated circuits, 140. Ceramic-based circuits, 141. Special types of printed circuits, 142.*

## **9 Vacuum Technology and the Flow of Gases, 145**

*Introduction, 145. Vacuum, pressure and gases, 146. Vacuum and pressure Units, 147. Vacuum technology and gases, 148. Fundamental laws of gases, 149. Evaporation—pump-down time, 151. Summary, 152. Vacuum pumps, 153. Compression type pumps, 154. Noncompression type pumps, 159. Gauges for vacuum measurement, 160. Thermal conductivity gauges, 164. Ionization gauges, 166. Vacuum systems and practical techniques, 167.*

## **10 Assembly and Packaging, 169**

*Introduction, 169. IC package types, 170. Die bonding, 173. Wire bonding, 180. Package materials, 184. Sealing and encapsulation, 187.*

## **11 Microscopes in IC Fabrication, 193**

*Introduction, 193. The eye and magnification, 195. The compound microscope, 198. Special microscope systems, 210. Microscope setup, 213.*

## **12 Digital and Linear IC Circuits, 215**

*Introduction, 215. Digital IC's, 216. Basic logic gating circuits, 216. Digital gate configurations, 223. Basic IC assemblies, 227. IC specifications and usage, 236. Operational amplifiers, 237.*

## **13 Test and Measurement of Integrated Circuits, 247**

*Approach, 247. Parameters—physical layout, 248. Probe testing, 249. Digital assembly testing, 249. Op Amp assembly testing, 259. Special IC assembly testing, 265.*

# 14 IC Equipment and Large Scale Integration, 269

*Introduction, 269. Engineering system development, 270. Large scale integration, 270. System approach to IC equipment, 290.*

## Appendices

301

- A Specific Material Resistances, 303**
- B Physical and Electrical Conversion Factors, 304**
- C Bare Copper Wire Tables, 306**
- D SI Physical and Electrical Symbols and Units, 308**
- E Glossary of Semiconductor Terms and Definitions, 310**
- F Transistor and Thyristor Symbols and Characteristics, 315**
- G Commonly Used Semiconductor Letters and Symbols, 316**
- H Component, Conventional, and LSI Chip Densities, 319**
- I IC Microwave Equipment and Measurement Techniques, 320**
- J The Darlington Amplifier—Theory and Design, 323**
- K “H” and “Y” Parameters in High-Frequency Transistor Measurement, 325**
- L Operational Amplifier Specifications, 328**
- M Microscope Depth Measurements, 330**
- N Properties of Thin-Film Dielectrics and Silicon Resistors, 333**
- O Operational Amplifier Glossary of Terms, 335**
- P Dark/Light Microscope Field Systems, 338**

## Index

341